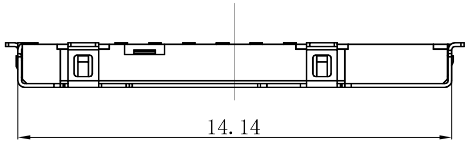
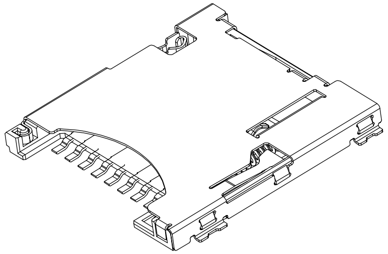
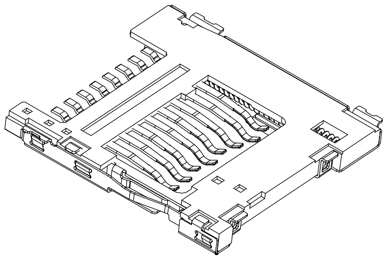
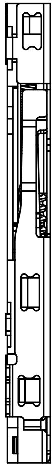
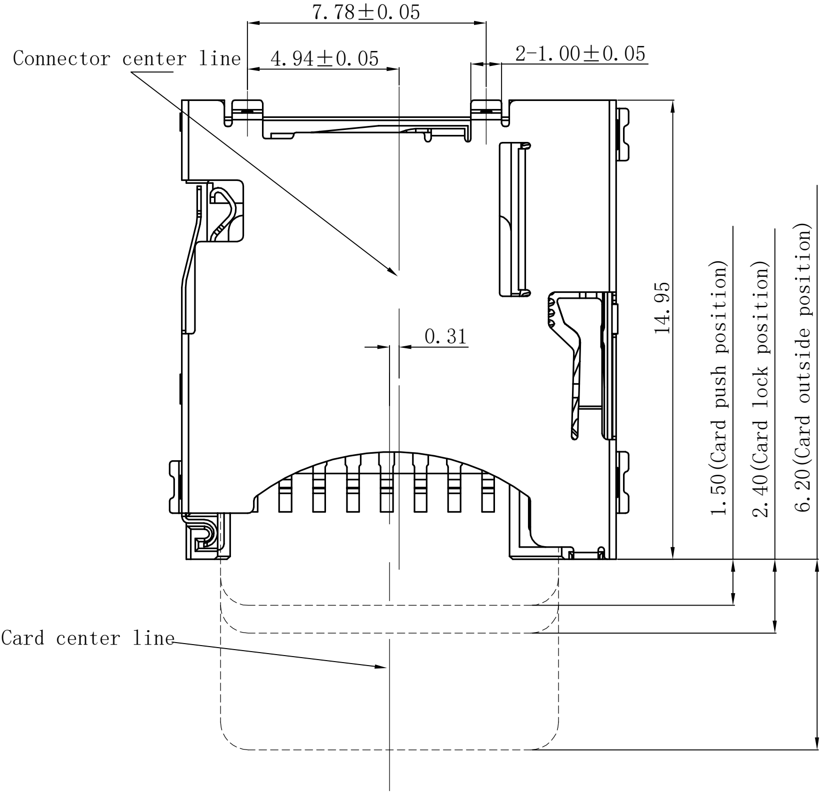
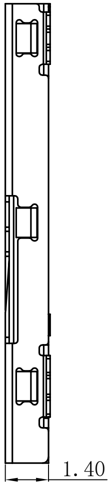


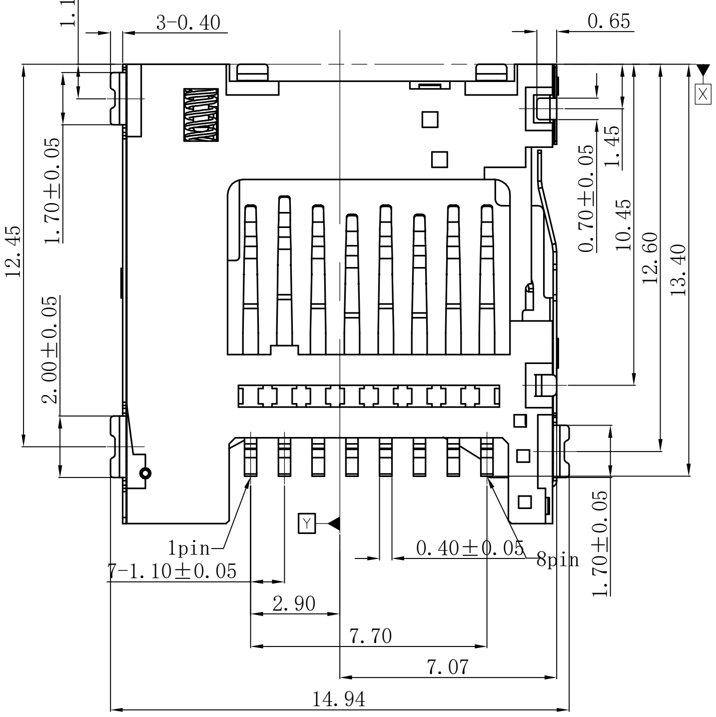


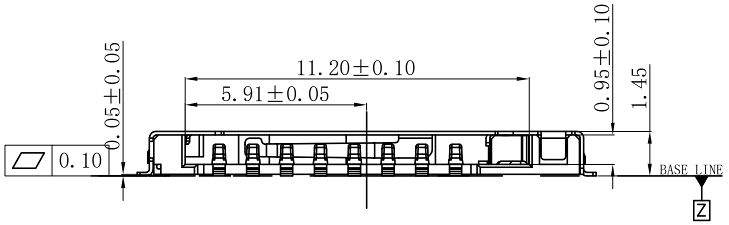










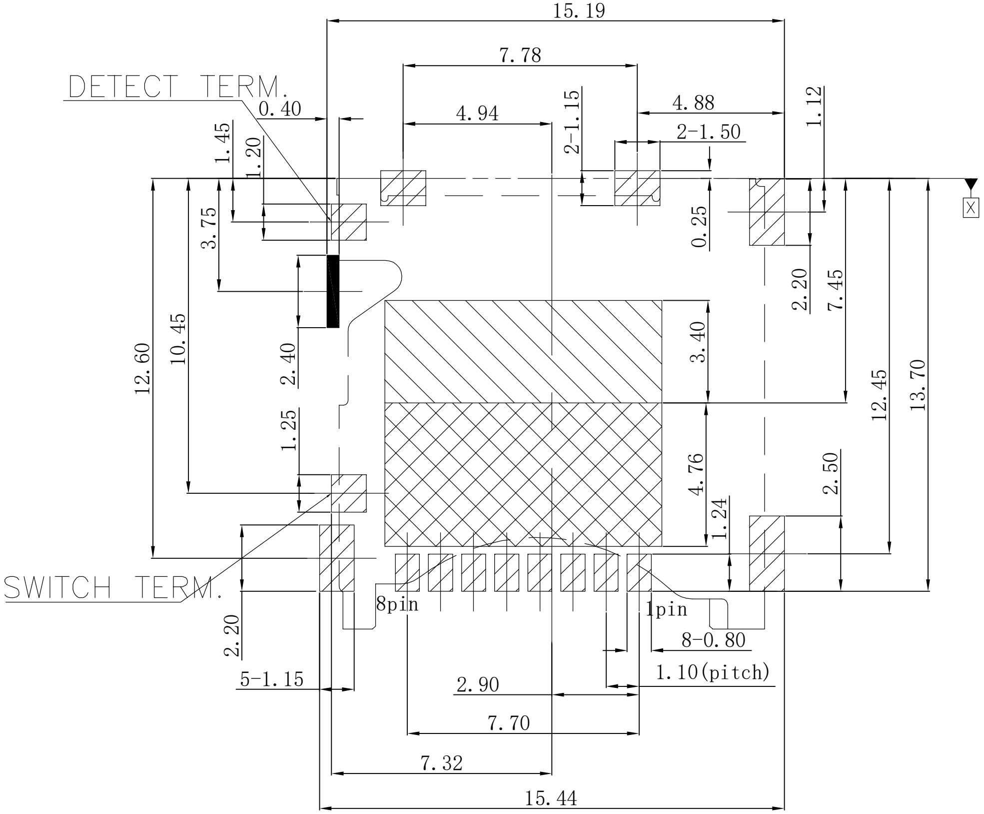


PIN	T/F CARD
	microSD
8	P8 Dat1
7	P7 Dat0
6	P6 VSS
5	P5 CLK
4	P4 VDD
3	P3 CMD
2	P2 CD/Dat3
1	P1 Dat2

HOAUC

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.° ±2° X.X° ±0.5°	DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF PUSH 内焊 1.4H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW97-TF08-140B MOLD NO.
UNIT: mm [inch]	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-TF17120395
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

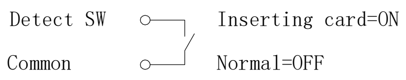
▨ PAD AREA

▧ PATTERN PROHIBITION AREA

▩ SOLDER PROHIBITION AREA

■ PROHIBITED AREA

Ciroult diagram for detect switch



Specification

1.MATERIAL:

1.1 Insulator:High Temperature Thermoplastic,
(LCP,MG350),UL Black 94V-0.

1.2 Contact: Phosphor Bronze(C5210R-H,T=0.15±0.03mm)

1.3 Shell: SUS304-H T=0.12±0.03mm

2.Plating:

2.1 Contact: Plated 50u''min Ni Overall
Plated 1u”min Au Selective contact area
Plated 100u”min Sn over Ni on solder area

2.2 Shell: Plated 50u''min Ni Overall
Plated 1u”min Au Selective Contact Area

3.Property:

3.1 Current Rating :0.5A AC/DC max.

3.2 Voltage Rating :3.3V/5V(AC/DC)

3.3 Contact Resistance:Contact Pin 100mΩ max.

3.4 Insert/Pulling Force: 40N Max / 0.5~40N

3.5 Smt Solder Temperature: Should Under 260°C

3.6 Operation Temperature Range: -40~+85°C

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